

Application No.: 09/577,932  
Amendment Under 37 C.F.R. §1.111 dated August 5, 2004  
Response to the Office Action of May 5, 2004

### **Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

### **Listing of Claims**

Claim 1 (Currently Amended): A semiconductor device comprising:

- a semiconductor element having a plurality of electrodes;
- a redistribution layer having a plurality of electrode pads and electrical conductive patterns connecting the electrodes of the semiconductor element to the respective electrode pads;
- a plurality of metal posts each with a first shape and a first size formed on the electrode pads of the redistribution layer, the metal posts being configured to be provided with external connection electrodes; and
- at least one mark member with a second shape and a second size which serves as an alignment mark located in a predetermined positional relationship with the metal posts,
- wherein the mark member is made of the same material as the metal posts; and
- wherein the first shape and the first size are correspondingly different from the second shape and the second size;
- wherein the metal posts have a flat top surface; and
- ~~wherein the metal posts would not melt in their ordinary usage.~~

Application No.: 09/577,932  
Amendment Under 37 C.F.R. §1.111 dated August 5, 2004  
Response to the Office Action of May 5, 2004

Claim 2 (Previously Presented): The semiconductor device as claimed in claim 1, wherein the alignment mark has an outer configuration other than a circle.

Claim 3 (Previously Presented): The semiconductor device as claimed in claim 1, wherein a width of the alignment mark measured along a plane parallel to a surface of the redistribution layer is greater than a height of the metal posts.

Claim 4 (Currently Amended): A semiconductor device comprising:  
a semiconductor element having a plurality of electrodes;  
a redistribution layer having a plurality of conductive patterns which connects the electrodes of the semiconductor device to a plurality of electrode pads each with a first shape and a first size located in predetermined positions of the redistribution layer; and  
at least one mark member with a second shape and a second size which serves as an alignment mark located in a predetermined positional relationship with the electrode pads;  
wherein the mark member is made of the same material as the electrode pads; and  
wherein the first shape and the first size are correspondingly different from the second shape and the second size;  
wherein the plurality of electrode pads have a flat top surface; and  
~~wherein the plurality of electrode pads would not melt in their ordinary usage.~~

Application No.: 09/577,932  
Amendment Under 37 C.F.R. §1.111 dated August 5, 2004  
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Claim 5 (Previously Presented): The semiconductor device as claimed in claim 4,  
wherein the alignment mark has an outer configuration other than a circle.

Claims 6-12 (canceled)

Claim 13 (Original): An apparatus for fixing a semiconductor wafer by suction,  
comprising:  
a vacuum chuck table having a porous plate overlaying a plurality of concentric suction  
grooves;  
a plurality of suction passages each being correspondingly connected to the plurality of  
concentric suction grooves; and  
each of the plurality of suction passages being connected to more than one hole on the  
porous plate;  
suctioning device for sequentially introducing a suctioning force into the suction passages  
at different timing.

Claim 14 (Currently Amended): A semiconductor device comprising:  
a semiconductor element having a plurality of electrodes;  
a redistribution layer having a plurality of electrode pads and electrical conductive  
patterns connecting the electrodes of the semiconductor element to the respective electrode pads;

Application No.: 09/577,932  
Amendment Under 37 C.F.R. §1.111 dated August 5, 2004  
Response to the Office Action of May 5, 2004

a plurality of metal posts with a first shape and a first size formed on the electrode pads of the redistribution layer, the metal posts being configured to be provided with external connection electrodes; and

at least one mark member with a second shape and a second size which serves as an alignment mark located in a predetermined positional relationship with the metal posts;

wherein the first shape and the first size are correspondingly different from the second shape and the second size;

wherein the metal posts have a flat top surface; ~~and~~

~~wherein the metal posts would not melt in their ordinary usage.~~

Claim 15 (Currently Amended): A semiconductor device comprising:

a semiconductor element having a plurality of electrodes;

a redistribution layer having a plurality of electrode pads and electrical conductive patterns connecting the electrodes of the semiconductor element to the respective electrode pads;

a plurality of metal posts formed on the electrode pads of the redistribution layer;

at least one electrode part comprising one of the metal posts and a protruding electrode attached to a top of the one of the metal posts; and

at least one mark member which serves as an alignment mark located in a predetermined positional relationship with the electrode part, the mark member comprising one of the metal posts but lacking the protruding electrode;

Application No.: 09/577,932  
Amendment Under 37 C.F.R. §1.111 dated August 5, 2004  
Response to the Office Action of May 5, 2004

wherein the metal posts have a flat top surface; and

~~wherein the metal posts would not melt in their ordinary usage.~~